



BERGQUIST® GAP PAD® TGP 7000ULM

ULTRA-LOW MODULUS, HIGH THERMAL CONDUCTIVITY GAP FILLING MATERIAL

BERGQUIST® GAP PAD® TGP 7000ULM is a high thermal conductivity, ultra-low modulus thermal interface material designed for modern telecom and datacom applications where high power densities are the norm. The soft, conforming characteristics of BERGQUIST® GAP PAD® TGP 7000ULM ensure excellent wet out at the interface even on rough or irregular surfaces, delivering optimized thermal transfer and minimizing assembly stress. A silicone-based resin platform and unique filler technology enable high, 7.0 W/m-K thermal conductivity while prioritizing stress reduction on miniaturized, delicate components. BERGQUIST® GAP PAD® TGP 7000ULM is supplied in easy-to-use pre-cut pads and has an inherent high tack on both sides.

Key Benefits

- Low assembly stress due to ultra-low modulus (Shore 000, ASTM D2240)
- Excellent conformability to rough or irregular surfaces
- Thorough wet out at the interface for maximized thermal transfer
- High thermal conductivity of 7.0 W/m·K
- Simplified application and processability; supplied in pre-cut, custom-sized pads with high tack on both sides
- Room-temperature storage



| PROPERTIES | | BERGQUIST® GAP PAD® TGP 7000ULM |
|-----------------------|--|---------------------------------|
| Physical Properties | Young's Modulus (kPa) | 152 |
| | Appearance | Gray |
| Thermal Properties | Thermal Conductivity (W/m·K) | 7.0 |
| Electrical Properties | Dielectric Breakdown Voltage (40 mil, VAC) | > 5,000 |
| | Volume Resistivity ($\Omega \cdot m$) | 1.2×10^{11} |
| Safety Testing | Flammability Rating | UL 94 V-0 |

Typical applications

- Telecommunications (routers, switches and base stations)
- Optical Transceivers
- ASICs and DSPs



**Across the Board,
Around the Globe.**
henkel-adhesives.com/thermal



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